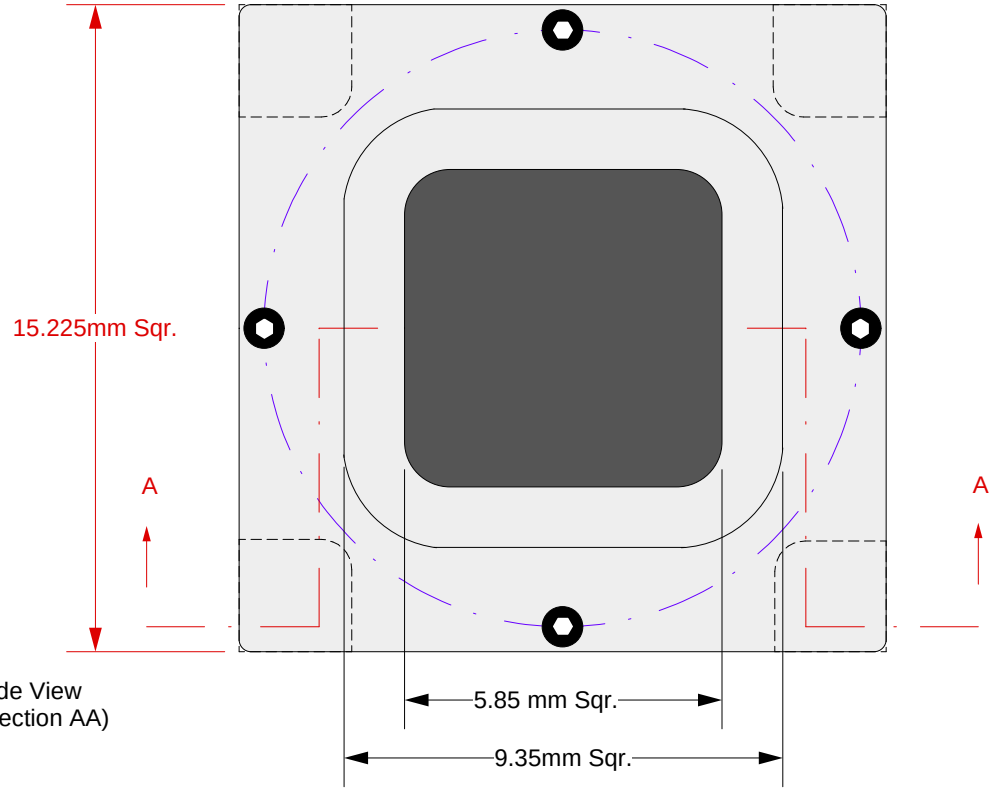
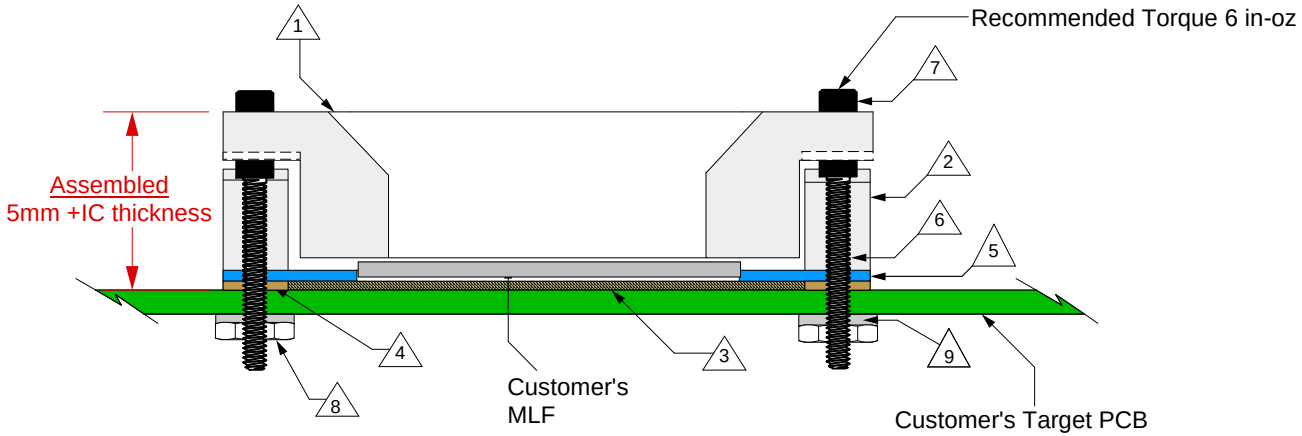
GHz MLF Socket - Direct mount, solderless

Top View



Side View
(Section AA)



Features

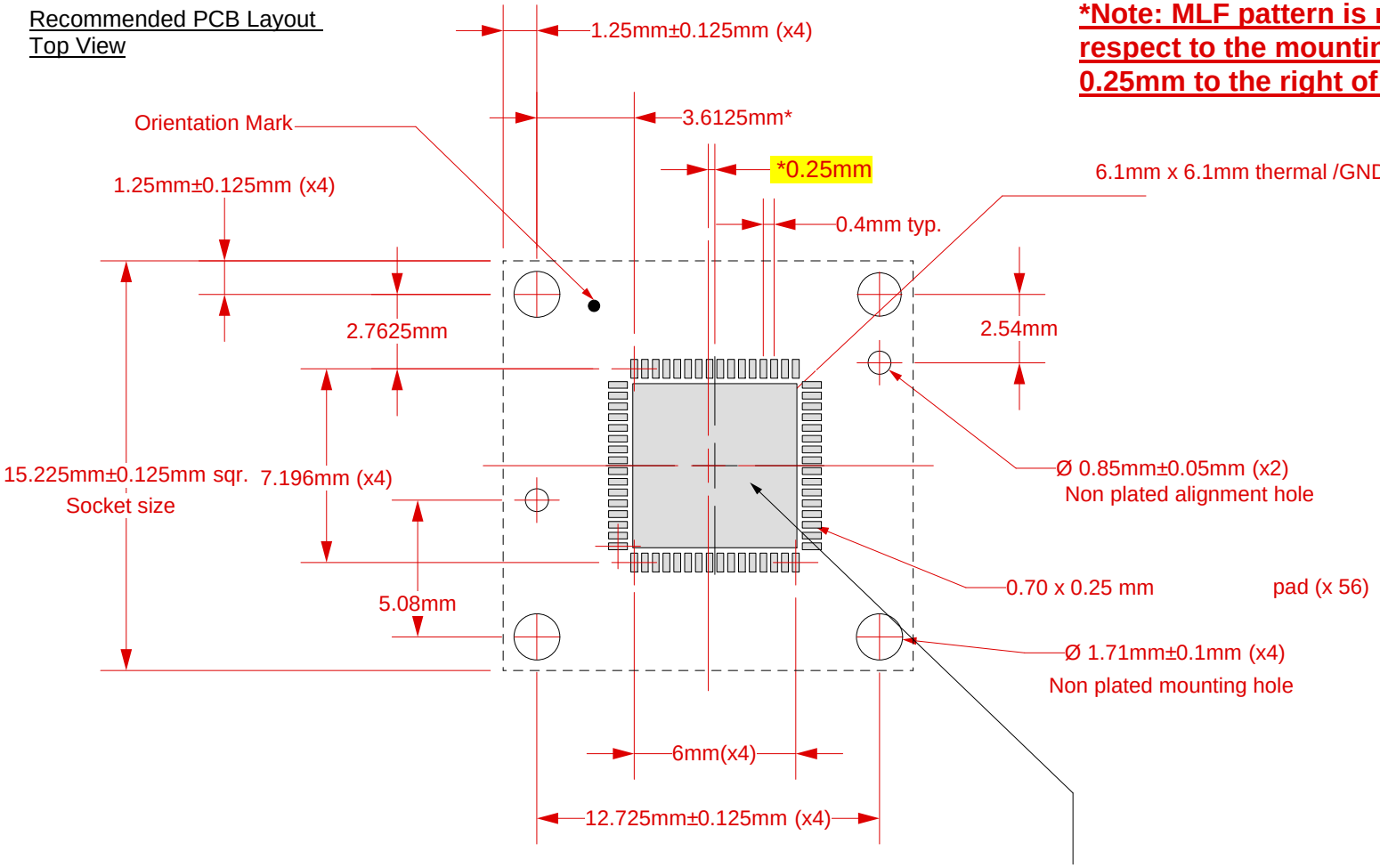
- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- IC guide prevents over compression of elastomer
- Open TOP socket lid

1	Socket Lid: Black anodized Aluminum. Thickness = 4.725mm.
2	Socket base: Black anodized Aluminum. Thickness = 3mm.
3	Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
4	Elastomer Guide: Cirlex Thickness = 0.475mm.
5	IC (MLF) Guide: Ultem1000
6	Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread , 7.94mm long.
7	Socket lid screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread , 4.76mm long.
8	Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
9	Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

SG-MLF-7072 Drawing	Status: Released	Scale: -	Rev: A
© 2012 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: S. Huang	Date: 8/10/12	
	File: SG-MLF-7072 Dwg.mcd	Modified:	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View



***Note: MLF pattern is not symmetrical with respect to the mounting holes. It is offset 0.25mm to the right of center.**

**** To effectively conduct heat away from the package a thermal pad is recommended with vias spaced 1.0 to 1.2 mm pitch and a diameter of 0.3 to 0.33 mm. Ideally 1 via for every 3 leads has been shown to work well.

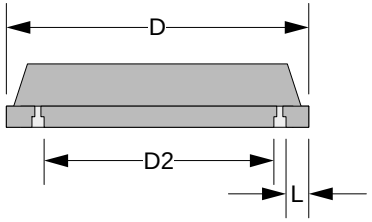
QFN64D

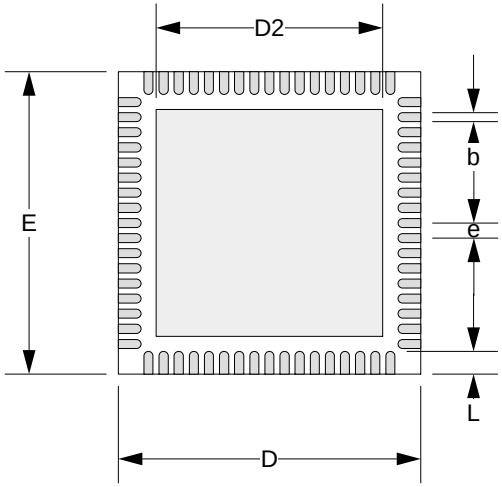
Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm unless stated otherwise.
All dimensions are in mm.

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Package Code	e	D min	D max	E min	E max	b min	b max	L min	L max	D2	N
QFN64D	0.4	7.4	7.6	7.4	7.6	0.18	0.3	0.3	0.5	6.2	64





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